- 3-State Outputs Drive Bus Lines Directly
- Flow-Through Architecture Optimizes PCB Layout
- Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-µm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, and Standard Plastic 300-mil DIPs (NT)

(TOP VIEW) 24 DIR Α1 A2 🛮 23 II B1 A3 🛮 3 22 **B**2 A4 🛮 4 21 **B**3 20 GND 5 Пв4 19 GND [] 6 18 🛮 V_{CC} GND 7 GND ∏8 17 🛮 B5 16 🛮 B6 A5 🛮 9 15 B7 A6 🛮 10 14 **B**8 A7 🛛 11

A8L

13 OE

DB. DW. NT. OR PW PACKAGE

description

This octal bus transceiver is designed for asynchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

The device allows noninverted data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so that the buses are effectively isolated.

The 74AC11245 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE

OUTPUT ENABLE OE	DIRECTION CONTROL DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	Х	Isolation

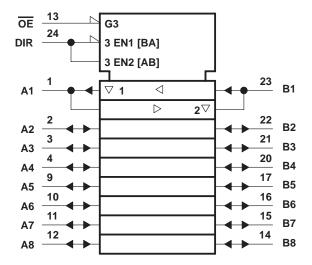


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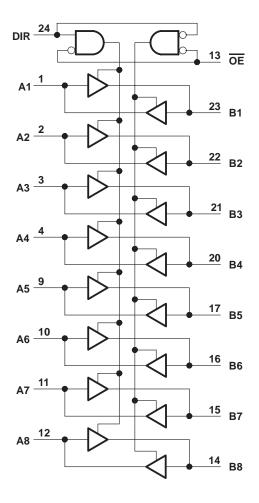


logic symbol†



 $[\]ensuremath{^{\dagger}}$ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	0.5 V to V _{CC} + 0.5 V
Output voltage range, VO (see Note 1)	-0.5 V to $V_{CC} + 0.5 \text{ V}$
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	±200 mA
Maximum power dissipation at $T_A = 55^{\circ}$ C (in still air) (see Note 2): DB package 0.65 W
•	DW package1.7 W
	NT package
	PW package 0.7 W
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150 °C and a board trace length of 750 mils, except for the NT package, which has a trace length of zero.

recommended operating conditions

			MIN	NOM	MAX	UNIT	
Vcc	Supply voltage		3	5	5.5	V	
		V _{CC} = 3 V	2.1				
ViH	High-level input voltage	V _{CC} = 4.5 V	3.15			V	
		V _{CC} = 5.5 V	3.85				
		V _{CC} = 3 V			0.9		
VIL	Low-level input voltage	V _{CC} = 4.5 V			1.35	V	
		V _{CC} = 5.5 V			1.65		
VI	Input voltage		0		VCC	V	
Vo	Output voltage		0		VCC	V	
		V _{CC} = 3 V			-4		
ІОН	High-level output current	V _{CC} = 4.5 V			-24	mΑ	
		V _{CC} = 5.5 V			-24		
		V _{CC} = 3 V			12		
lOL	Low-level output current	V _{CC} = 4.5 V			24	mA	
		V _{CC} = 5.5 V			24		
Δt/Δν	Input transition rise or fall rate		0		10	ns/V	
TA	Operating free-air temperature		-40		85	°C	



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T _A = 25°C			MIN	MAV	UNIT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	IVIIIV	0.1 0.1 0.1 0.44 0.44 1.65 ±5 ±1 80	UNII
		3 V	2.9			2.9		
	I _{OH} = -50 μA	4.5 V	4.4			4.4		
		5.5 V	5.4			5.4		
Voн	I _{OH} = -4 mA	3 V	2.58			2.48		V
	Jan - 24 mA	4.5 V	3.94			3.8		
	IOH = -24 MA	5.5 V	4.94			4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85		
		3 V			0.1		0.1	
	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	4.5 V			0.1		0.1	
VOL	I _{OL} = 12 mA	3 V			0.36		0.44	V
	la. 24 mA	4.5 V			0.36		0.44	
	IOL = 24 IIIA	5.5 V			0.36		0.44	
	I _{OL} = 75 mA [†]	5.5 V					1.65	
A or B ports‡	Va Va a or CND	E E V			±0.5		±5	A
OE or DIR	AD = ACC OL GND	5.5 V			±0.1	±1		μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80	μА
C _i	V _I = V _{CC} or GND	5 V		4				pF
C _{io}	$V_O = V_{CC}$ or GND	5 V		12				рF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO T _A = 25°C			MIN MAX	MAX	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX		IVIAA	UNIT
^t PLH	A or B	B or A	1.5	6.5	11.2	1.5	12.5	ns
^t PHL			1.5	5.7	8.5	1.5	9.7	
^t PZH		B or A	1.5	8.6	14.2	1.5	15.9	ne
t _{PZL}	ŌĒ	JE BOIA	1.5	8.2	11.5	1.5	12.7	ns
t _{PHZ}	ŌĒ	B or A	1.5	7.7	10.5	1.5	11.3	ne
^t PLZ		BULA	1.5	8.5	12	1.5	13	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	TO T _A = 25°C			MIN	MAV	UNIT
PARAMETER (INPUT) (OUTPUT)		MIN	TYP	MAX	MAX		UNIT	
^t PLH	A or B	B or A	1.5	4.8	8.5	1.5	9.5	ns
^t PHL		BOIA	1.5	4.1	6.3	1.5	6.9	115
^t PZH	ŌĒ	B or A	1.5	6.2	10.2	1.5	11.4	ns
^t PZL		BUIA	1.5	5.9	8.6	1.5	9.5	115
^t PHZ	ŌĒ	B or A	1.5	6.4	8.8	1.5	9.5	ne
^t PLZ		D OI A	1.5	7	9.6	1.5	10.4	ns

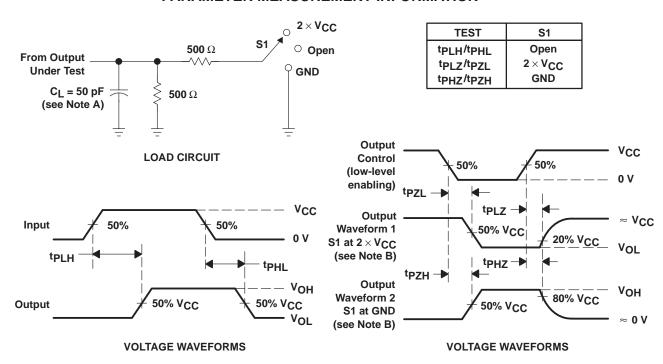


[‡] For I/O ports, the parameter IOZ includes the input leakage current.

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

PARAMETER			TEST CO	TYP	UNIT	
C _{pd} Power dissipation capacitance per transceiver	Down dissination conscitance per transcriver	Outputs enabled	C 50 pE	f = 1 MHz	64	рF
	Power dissipation capacitance per transceiver	Outputs disabled	$C_L = 50 \text{ pF},$	1 = 1 IVITIZ	16	

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_f = 3 \text{ ns}$, $t_f = 3 \text{ ns}$.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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